

## **Quarterly Reliability Monitoring Results**

## Quarters: Q1/2021 to Q4/2021

Based on structural similarity

| Supplier Nexperia B.V. Name of Laboratory |  | User Part Number PESD12VS1UJ Part Description   |                                   |           |            |           |  |                           |  |               |            |  |  |  |
|---|--|---|-----------------------------------|-----------|------------|-----------|--|---------------------------|--|---------------|------------|--|--|--|
|   |  |   |                                   |           |            |           |  |                           |  | Nexperia DHAM | Protection |  |  |  |
|   |  |   |                                   |           |            |           |  | Assembly reliability labs |  | SMD package   |            |  |  |  |
| Based on AEC-Q101 Test                    |  | Test Conditions   | Duration                          | # Lots    | # Quantity | # Rejects |  |                           |  |               |            |  |  |  |
|   | TEST Pre- and Post-Stress                                |   |                                   |           |            |           |  |                           |  |               |            |  |  |  |
| # E1                                      | Electrical Test  | Tamb = 25 °C  | N/A                               | see below | all parts  | see below |  |                           |  |               |            |  |  |  |
| # A1                                      | <b>PC</b> Preconditioning                                | JESD22-A113<br>Bake Tamb = 125 °C<br>Soak Tamb = 85 °C, RH = 85%<br>Reflow soldering                | 24 hours<br>168 hours<br>3 cycles | 286       | 21480      | 0         |  |                           |  |               |            |  |  |  |
| # B1                                      | HTRB<br>High Temperature Reverse<br>Bias                 | MIL-STD-750-1<br>M1038 Method A<br>Tj = Tjmax, Vr = 100% of max. datasheet<br>reverse voltage       | 1000 hours                        | 117       | 9360       | 0         |  |                           |  |               |            |  |  |  |
| # A4                                      | TC Temperature Cycling                                   | JESD22-A104<br>-65 °C to Tjmax, not to exceed 150°C   | 1000 cycles                       | 86        | 6880       | 0         |  |                           |  |               |            |  |  |  |
| # A3 alt                                  | <b>AC</b><br>Autoclave                                   | JESD22-A102<br>Tamb = 121 °C, RH = 100 %<br>Pressure = 205 kPa (29.7 psia)                          | 96 hours                          | 86        | 6880       | 0         |  |                           |  |               |            |  |  |  |
| # A2 alt                                  | <b>H3TRB</b> High Humidity High Temperature Reverse Bias | JESD22-A101<br>Tamb = 85 °C, RH = 85%, VR = 80 % of rated reverse voltage <sup>[1]</sup>            | 1000 hours                        | 86        | 6880       | 0         |  |                           |  |               |            |  |  |  |
| # A5                                      | <b>IOL</b> Intermittent Operating Life                   | MIL-STD-750 Method 1037 ton = toff, devices powered to insure $\Delta Tj = 100$ °C for 15000 cycles | 1000 hours                        | n.a.      | n.a.       | n.a.      |  |                           |  |               |            |  |  |  |
| # C8                                      | <b>RSH</b><br>Resistance to Solder Heat                  | JESD22-A111<br>260 °C ± 5 °C  | 10 s                              | 28        | 840        | 0         |  |                           |  |               |            |  |  |  |
| # C10                                     | <b>SD</b><br>Solderability                               | J-STD-002   |                                   | 36        | 360        | 0         |  |                           |  |               |            |  |  |  |

[1]The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

## **Calculation of FIT and MTTF**

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1)
Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

| Wafer Fab | Technology | Quantity | Rejects | Failure Rate (FIT) | MTTF (hrs) |
|-----------|------------|----------|---------|--------------------|------------|
| Nexperia  |            |          |         |                    |            |
| DHAM      | Protection | 9360     | 0       | 0.45               | 2.20E+09   |

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